Zener Voltage Regulators

200 mW SOD-923 Surface Mount

This series of Zener diodes is packaged in a SOD-923 surface mount package. They are designed to provide voltage regulation protection and are especially attractive in situations where space is at a premium. They are well suited for applications such as cellular phones, hand held portables, and high density PC boards.

Specification Features

- Standard Zener Breakdown Voltage Range –2.4 V to 18 V
- Steady State Power Rating of 200 mW
- Small Body Outline Dimensions: 0.039" x 0.024" (1.00 mm x 0.60 mm)
- Low Body Height: 0.016" (0.40 mm)
- ESD Rating of Class 3 (>16 kV) per Human Body Model
- Tight Tolerance V_Z
- These are Pb-Free Devices

Mechanical Characteristics

CASE: Void-free, transfer-molded, thermosetting plastic

Epoxy Meets UL 94, V-0

LEAD FINISH: 100% Matte Sn (Tin)

MOUNTING POSITION: Any

QUALIFIED MAX REFLOW TEMPERATURE: 260°C

Device Meets MSL 1 Requirements

MAXIMUM RATINGS

Rating	Symbol	Max	Unit	
Total Device Dissipation FR-5 Board, (Note 1) @ T _A = 25°C Derate above 25°C	P _D	200 1.5	mW mW/°C	
Thermal Resistance from Junction-to-Ambient	$R_{\theta JA}$	635	°C/W	
Junction and Storage Temperature Range	T _J , T _{stg}	-65 to +150	°C	

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

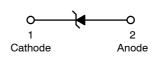
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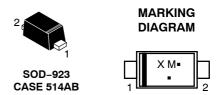
1. FR-4 Minimum Pad.



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X = Specific Device Code

M = Month Code

= Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping†
NZ9FxxxST5G	SOD-923 (Pb-Free)	8000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

DEVICE MARKING INFORMATION

See specific marking information in the device marking column of the Electrical Characteristics table on page 3 of this data sheet.

ELECTRICAL CHARACTERISTICS

 $(T_A = 25^{\circ}C \text{ unless otherwise noted,}$ $V_F = 0.9 \text{ V Max.} @ I_F = 10 \text{ mA for all types)}$

Symbol	Parameter					
VZ	Reverse Zener Voltage @ I _{ZT}					
I _{ZT}	Reverse Current					
Z _{ZT}	Maximum Zener Impedance @ I _{ZT}					
I _{ZK}	Reverse Current					
Z _{ZK}	Maximum Zener Impedance @ I _{ZK}					
I _R	Reverse Leakage Current @ V _R					
V _R	Reverse Voltage					
I _F	Forward Current					
V _F	Forward Voltage @ I _F					
ΘV _Z	Maximum Temperature Coefficient of V _Z					
С	Max. Capacitance @V _R = 0 and f = 1 MHz					

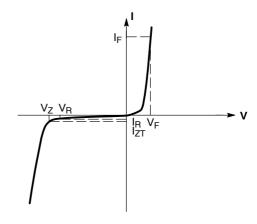


Figure 1. Zener Voltage Regulator

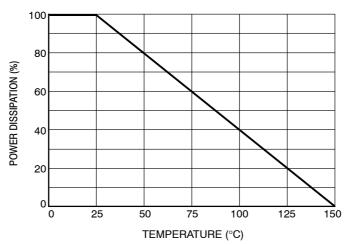


Figure 2. Steady State Power Derating

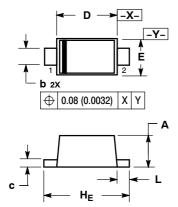
ELECTRICAL CHARACTERISTICS ($V_F = 0.9 \text{ Max} \circledcirc I_F = 10 \text{ mA}$ for all types)

		Zener V	/oltage Z	Test	Z _{ZT} I _Z = IZT @ 10%	Z _{ZK} I _Z = 1.0		Max IR @ VR		d _{VZ} /dt @ l _{ZT1}		CpF Max @
Device	Device Marking	Min	Max	Current Izt mA	Mod Ω Max	mA Ω Max	I _{ZK} mA	μА	V	Min	Max	V _R = 0 f = 1 MHz
NZ9F2V4ST5G	2*	2.43	2.63	5	100	1000	1	50	1	-3.5	0	210
NZ9F2V7ST5G	3*	2.67	2.91	5	100	1000	1	20	1	-3.5	0	210
NZ9F3V0ST5G	4*	2.94	3.26	5	100	1000	1	10	1	-3.5	0	210
NZ9F3V3ST5G	5*	3.32	3.53	5	100	1000	1	10	1	-3.5	0	210
NZ9F3V6ST5G	6*	3.6	3.85	5	100	1000	1	10	1	-3.5	0	210
NZ9F3V9ST5G	A**	3.89	4.16	5	100	1000	1	5	1	-3.5	-2.5	210
NZ9F4V3ST5G	D**	4.17	4.43	5	100	1000	1	5	1	-3.5	0	210
NZ9F4V7ST5G	E**	4.55	4.75	5	100	800	0.5	2	1	-3.5	0.2	150
NZ9F5V1ST5G	F**	4.989	5.2	5	80	500	0.5	2	1.5	-2.7	1.2	130
NZ9F5V6ST5G	J**	5.49	5.73	5	60	200	0.5	1	2.5	-2.0	2.5	115
NZ9F6V2ST5G	K**	6.06	6.33	5	60	100	0.5	1	3	0.4	3.7	110
NZ9F6V8ST5G	L**	6.65	6.93	5	40	60	0.5	0.5	3.5	1.2	4.5	105
NZ9F7V5ST5G	P**	7.28	7.6	5	30	60	0.5	0.5	4	2.5	5.3	100
NZ9F8V2ST5G	Q**	8.02	8.36	5	30	60	0.5	0.5	5	3.2	6.2	90
NZ9F9V1ST5G	R**	8.85	9.23	5	30	60	0.5	0.5	6	3.8	7	80
NZ9F10VST5G	T**	9.77	10.21	5	30	60	0.5	0.1	7	4.5	8	80
NZ9F11VST5G	V**	10.76	11.22	5	30	60	0.5	0.1	8	5.4	9	80
NZ9F12VST5G	Y**	11.74	12.24	5	30	80	0.5	0.1	9	6	10	80
NZ9F13VST5G	2**	12.91	13.49	5	37	80	0.5	0.1	10	7	11	75
NZ9F15VST5G	3**	14.34	14.98	5	42	80	0.5	0.1	11	9.2	13	70
NZ9F16VST5G	4**	15.85	16.51	5	50	80	0.5	0.1	12	10.4	14	65
NZ9F18VST5G	5**	17.56	18.35	5	50	80	0.5	0.1	14	12.4	16	60

^{*}Rotated 90°. **Rotated 180°.

PACKAGE DIMENSIONS

SOD-923 CASE 514AB-01 ISSUE B

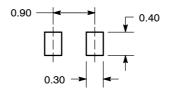


NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI
 Y14.5M. 1982.
- 2. CONTROLLING DIMENSION: MILLIMETERS.
- 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

	MIL	LIMETE	ERS	INCHES				
DIM	MIN	NOM	MAX	MIN	NOM	MAX		
Α	0.34	0.37	0.40	0.013	0.015	0.016		
b	0.15	0.20	0.25	0.006	0.008	0.010		
С	0.07	0.12	0.17	0.003	0.005	0.007		
D	0.75	0.80	0.85	0.030	0.031	0.033		
E	0.55	0.60	0.65	0.022	0.024	0.026		
HE	0.95	1.00	1.05	0.037	0.039	0.041		
L	0.05	0.10	0.15	0.002	0.004	0.006		

SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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